Customer Number: 20277

Case Docket Number: 67161-134

UTILITY PATENT APPLICATION UNDER 37 CFR 1.53(b)

Mail Stop Patent Application Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 Sir:



Transmitted herewith for filing is the patent application of:

INVENTOR: Koyu ASAI, Hiroshi TOBIMATSU, Hiroyuki KAWATA, Mahito

SAWADA

FOR: INTERCONNECTION STRUCTURE OF SEMICONDUCTOR DEVICE

Enclosed are:

\boxtimes	15 pages of specification, claims, abstract.						
\boxtimes	Declaration and Power of Attorney.						
\boxtimes	Priority Claimed.						
	Certified copy of Japanese Patent Application No. 2003-165013(P)						
\boxtimes	6 sheets of formal drawing.						
\boxtimes	An assignment of the invention to RENESAS TECHNOLOGY CORP.						
	and the assignment recordation fee.						
	An associate power of attorney.						
	A verified statement to establish small entity status under 37 CFR 1.9 and 37 CFR 1.27.						
\boxtimes	Information Disclosure Statement, Form PTO-1449 and references.						
Ħ	Return Receipt Postcard						

The filing fee has been calculated as shown below:

	NO. OF		EXTRA		
	CLAIMS		CLAIMS	RATE	AMOUNT
Total Claims	6	-20	0	\$18.00	\$0.00
Independent Claims	1	-3	0	\$86.00	\$0.00
	ependent Claim(s)	\$0.00			
	Basic Fee	\$770.00			
	bove Calculations	\$770.00			
	½ for Small Entity	\$0.00			
	t & Recording Fee	\$40.00			
				Total Fee:	\$810.00

Any filing fees under 37 CFR 1.16 for presentation of extra claims.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

Stephen A. Becker Registration No. 26,527

600 13th Street, N.W. Washington, DC 20005-3096 (202) 756-8000 SAB:tlb Facsimile: (202) 756-8087

Date: December 2, 2003